

# NCP551

## 150 mA CMOS Low Iq Low-Dropout Voltage Regulator

The NCP551 series of fixed output low dropout linear regulators are designed for handheld communication equipment and portable battery powered applications which require low quiescent. The NCP551 series features an ultra-low quiescent current of 4.0  $\mu$ A. Each device contains a voltage reference unit, an error amplifier, a PMOS power transistor, resistors for setting output voltage, current limit, and temperature limit protection circuits.

The NCP551 has been designed to be used with low cost ceramic capacitors and requires a minimum output capacitor of 0.1  $\mu$ F. The device is housed in the micro-miniature TSOP-5 surface mount package. Standard voltage versions are 1.5, 1.8, 2.5, 2.7, 2.8, 3.0, 3.3, and 5.0 V. Other voltages are available in 100 mV steps.

### Features

- Low Quiescent Current of 4.0  $\mu$ A Typical
- Maximum Operating Voltage of 12 V
- Minimum Output Capacitance of 1.0  $\mu$ F
- Low Output Voltage Option
- High Accuracy Output Voltage of 2.0%
- Industrial Temperature Range of  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$

### Typical Applications

- Battery Powered Instruments
- Hand-Held Instruments
- Camcorders and Cameras

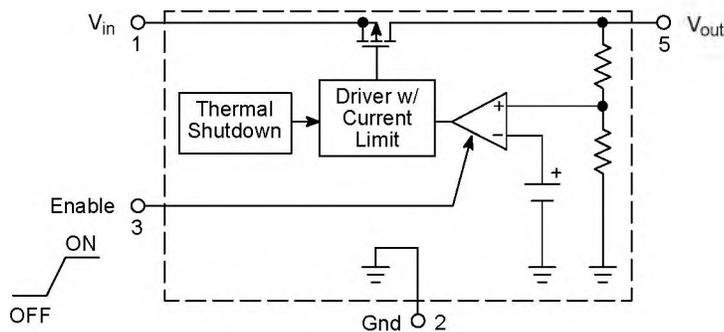
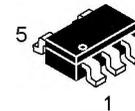


Figure 1. Representative Block Diagram



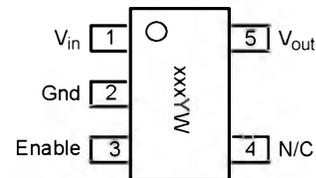
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TSOP-5  
(SOT23-5, SC59-5)  
SN SUFFIX  
CASE 483

### PIN CONNECTIONS AND MARKING DIAGRAM



xxx = Version  
Y = Year  
W = Work Week

(Top View)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 448 of this data sheet.

# NCP551

## PIN FUNCTION DESCRIPTION

Pin No.	Pin Name	Description
1	V <sub>in</sub>	Positive power supply input voltage
2	Gnd	Power supply ground
3	Enable	This input is used to place the device into low-power standby. When this input is pulled low, the device is disabled. If this function is not used, Enable should be connected to V <sub>in</sub> .
4	N/C	No Internal Connection
5	V <sub>out</sub>	Regulated output voltage

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage	V <sub>in</sub>	0 to 12	V
Enable Voltage	V <sub>EN</sub>	-0.3 to V <sub>in</sub> +0.3	V
Output Voltage	V <sub>out</sub>	-0.3 to V <sub>in</sub> +0.3	V
Power Dissipation and Thermal Characteristics			
Power Dissipation	P <sub>D</sub>	Internally Limited	W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	250	°C/W
Operating Junction Temperature	T <sub>J</sub>	+125	°C
Operating Ambient Temperature	T <sub>A</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Lead Soldering Temperature @ 260°C	T <sub>solder</sub>	10	sec

- This device series contains ESD protection and exceeds the following tests:  
Human Body Model 2000 V per MIL-STD-883, Method 3015  
Machine Model Method 200 V
- Latch up capability (85°C) ± 100 mA DC with trigger voltage.

# NCP551

## ELECTRICAL CHARACTERISTICS

( $V_{in} = V_{out(nom.)} + 1.0\text{ V}$ ,  $V_{EN} = V_{in}$ ,  $C_{in} = 1.0\ \mu\text{F}$ ,  $C_{out} = 1.0\ \mu\text{F}$ ,  $T_J = 25^\circ\text{C}$ , unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
Output Voltage ( $T_A = 25^\circ\text{C}$ , $I_{out} = 10\text{ mA}$ ) 1.5 V 1.8 V 2.5 V 2.7 V 2.8 V 3.0 V 3.3 V 5.0 V	$V_{out}$	1.455 1.746 2.425 2.646 2.744 2.94 3.234 4.90	1.5 1.8 2.5 2.7 2.8 3.0 3.3 5.0	1.545 1.854 2.575 2.754 2.856 3.06 3.366 5.10	V
Output Voltage ( $T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$ , $I_{out} = 10\text{ mA}$ ) 1.5 V 1.8 V 2.5 V 2.7 V 2.8 V 3.0 V 3.3 V 5.0 V	$V_{out}$	1.440 1.728 2.400 2.619 2.716 2.910 3.201 4.850	1.5 1.8 2.5 2.7 2.8 3.0 3.3 5.0	1.560 1.872 2.600 2.781 2.884 3.09 3.399 5.150	V
Line Regulation ( $V_{in} = V_{out} + 1.0\text{ V}$ to $12\text{ V}$ , $I_{out} = 10\text{ mA}$ )	$Reg_{line}$	–	10	30	mV
Load Regulation ( $I_{out} = 10\text{ mA}$ to $150\text{ mA}$ )	$Reg_{load}$	–	40	65	mV
Output Current 1.5 V, 1.8 V ( $V_{in} = 4.0\text{ V}$ ) 2.5 V, 2.7 V, 2.8 V, 3.0 V ( $V_{in} = 5.0\text{ V}$ ) 3.3 V ( $V_{in} = 6.0\text{ V}$ ) 5.0 V ( $V_{in} = 8.0\text{ V}$ )	$I_{o(nom.)}$	150 150 150 150	– – – –	– – – –	mA
Dropout Voltage ( $I_{out} = 10\text{ mA}$ , Measured at $V_{out} -3.0\%$ ) 1.5 V, 1.8 V, 2.5 V 2.7 V, 2.8 V, 3.0 V, 3.3 V, 5.0 V	$V_{in}-V_{out}$	– –	130 40	220 150	mV
Quiescent Current (Enable Input = 0 V) (Enable Input = $V_{in}$ , $I_{out} = 1.0\text{ mA}$ to $I_{o(nom.)}$ )	$I_Q$	– –	0.1 4.0	1.0 8.0	$\mu\text{A}$
Output Voltage Temperature Coefficient	$T_C$	–	$\pm 100$	–	ppm/ $^\circ\text{C}$
Enable Input Threshold Voltage (Voltage Increasing, Output Turns On, Logic High) (Voltage Decreasing, Output Turns Off, Logic Low)	$V_{th(en)}$	1.3 –	– –	– 0.3	V
Output Short Circuit Current 1.5 V, 1.8 V ( $V_{in} = 4.0\text{ V}$ ) 2.5 V, 2.7 V, 2.8 V, 3.0 V ( $V_{in} = 5.0\text{ V}$ ) 3.3 V ( $V_{in} = 6.0\text{ V}$ ) 5.0 V ( $V_{in} = 8.0\text{ V}$ )	$I_{out(max)}$	160 160 160 160	350 350 350 350	600 600 600 600	mA

3. Maximum package power dissipation limits must be observed.

$$PD = \frac{T_J(max) - T_A}{R_{\theta JA}}$$

4. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

## DEFINITIONS

### Load Regulation

The change in output voltage for a change in output current at a constant temperature.

### Dropout Voltage

The input/output differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 3% below its nominal. The junction temperature, load current, and minimum input supply requirements affect the dropout level.

### Maximum Power Dissipation

The maximum total dissipation for which the regulator will operate within its specifications.

### Quiescent Current

The quiescent current is the current which flows through the ground when the LDO operates without a load on its output: internal IC operation, bias, etc. When the LDO becomes loaded, this term is called the Ground current. It is actually the difference between the input current (measured through the LDO input pin) and the output current.

### Line Regulation

The change in output voltage for a change in input voltage. The measurement is made under conditions of low dissipation or by using pulse technique such that the average chip temperature is not significantly affected.

### Line Transient Response

Typical over and undershoot response when input voltage is excited with a given slope.

### Thermal Protection

Internal thermal shutdown circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When activated at typically 160°C, the regulator turns off. This feature is provided to prevent failures from accidental overheating.

### Maximum Package Power Dissipation

The maximum power package dissipation is the power dissipation level at which the junction temperature reaches its maximum operating value, i.e. 125°C. Depending on the ambient power dissipation and thus the maximum available output current.

# NCP551

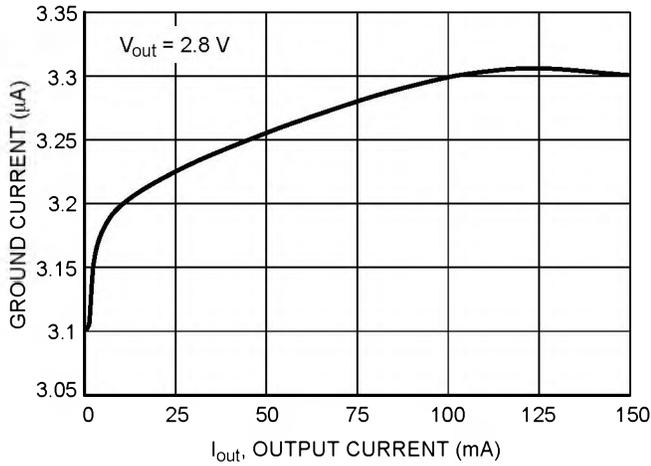


Figure 2. Ground Pin Current versus Output Current

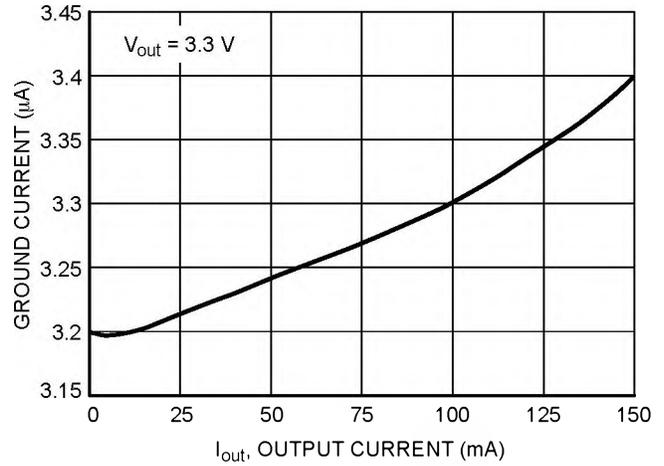


Figure 3. Ground Pin Current versus Output Current

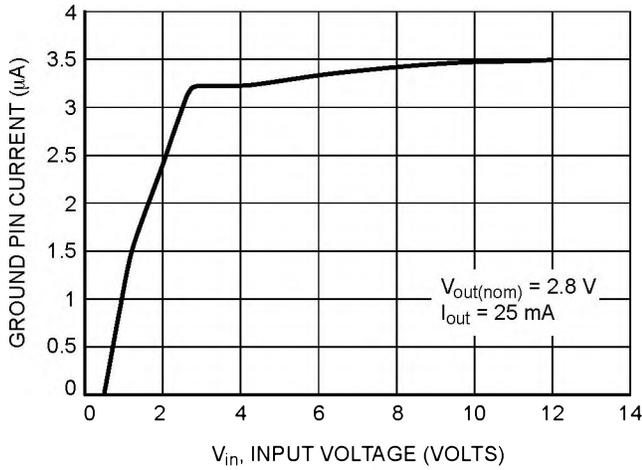


Figure 4. Ground Pin Current versus Input Voltage

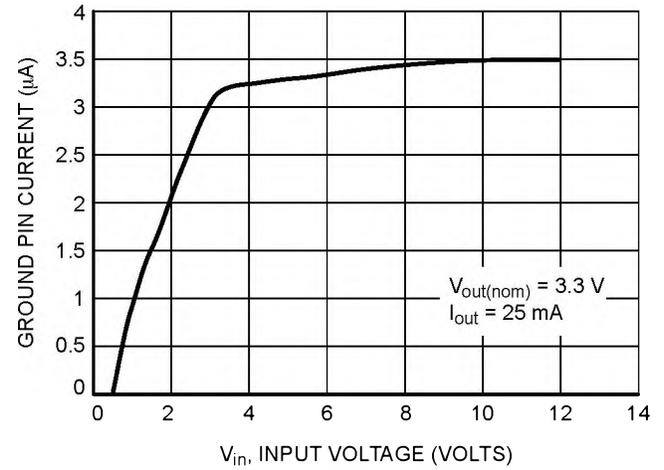


Figure 5. Ground Pin Current versus Input Voltage

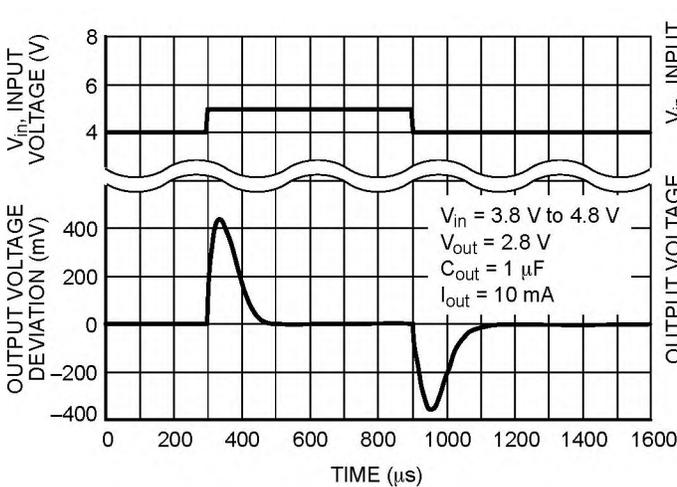


Figure 6. Line Transient Response

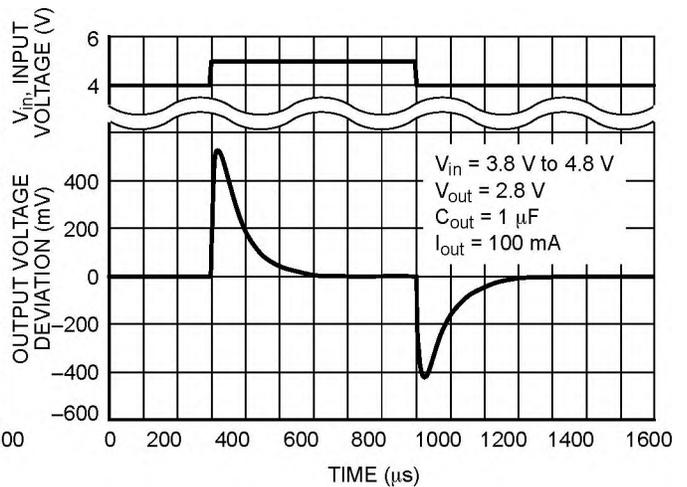


Figure 7. Line Transient Response

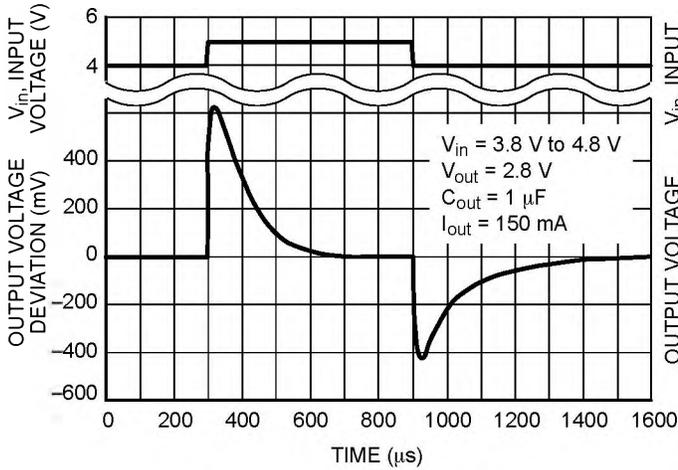


Figure 8. Line Transient Response

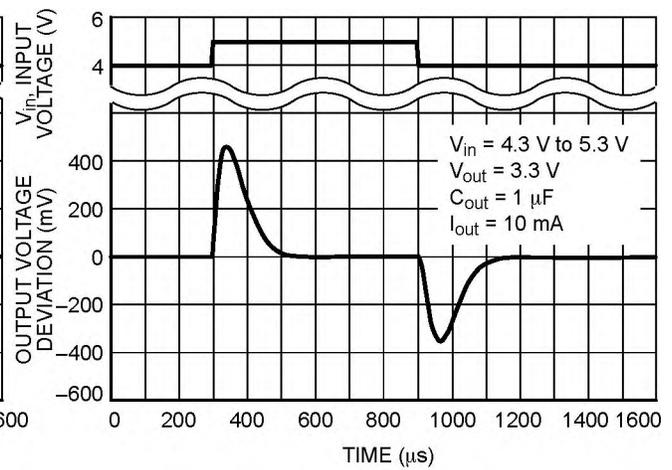


Figure 9. Line Transient Response

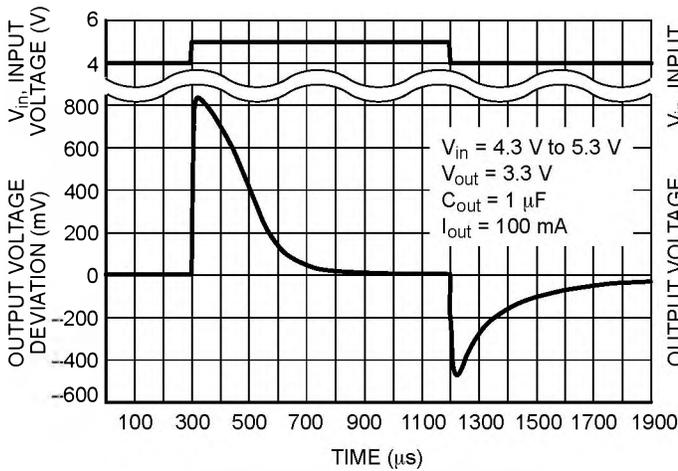


Figure 10. Line Transient Response

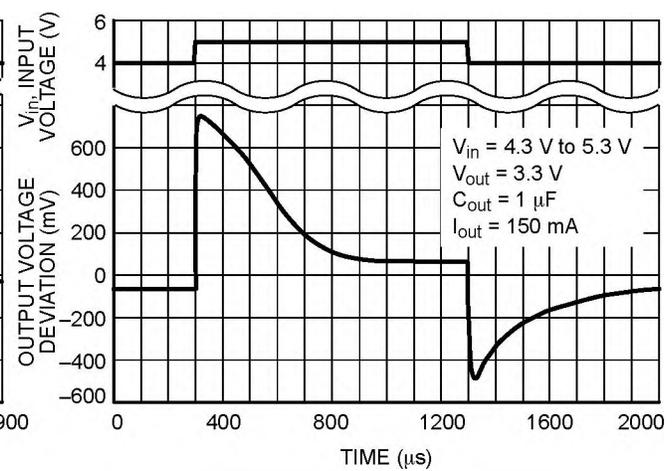


Figure 11. Line Transient Response

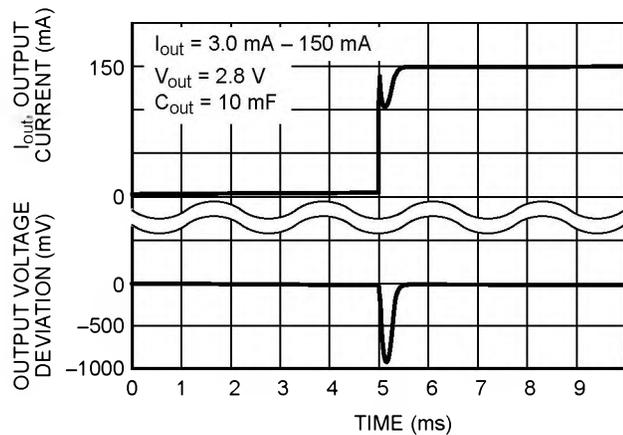


Figure 12. Load Transient Response ON

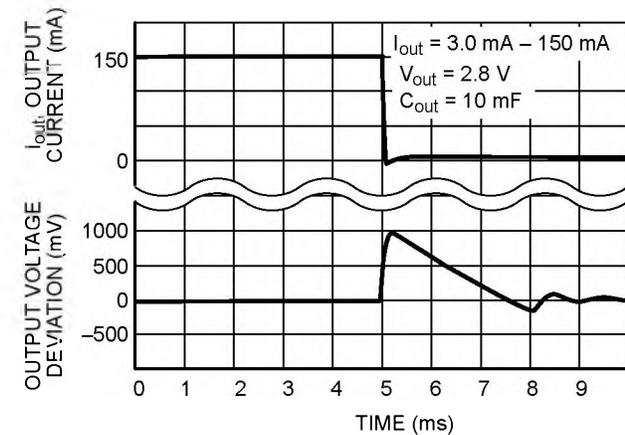


Figure 13. Load Transient Response OFF

# NCP551

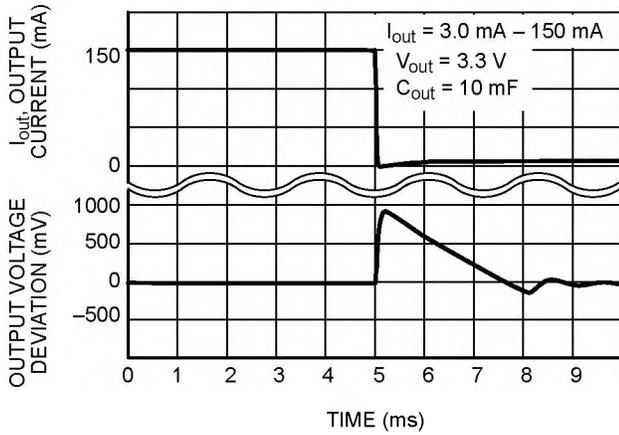


Figure 14. Load Transient Response OFF

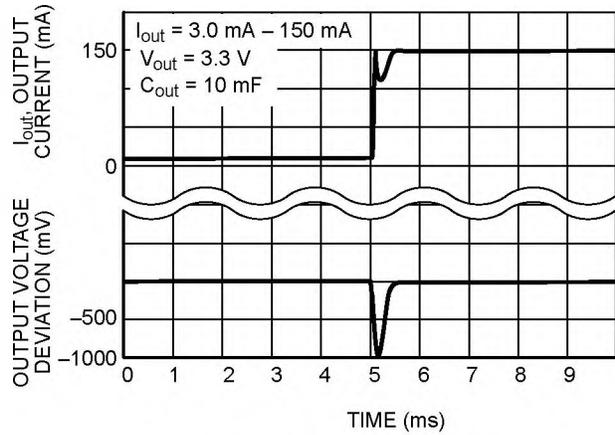


Figure 15. Load Transient Response ON

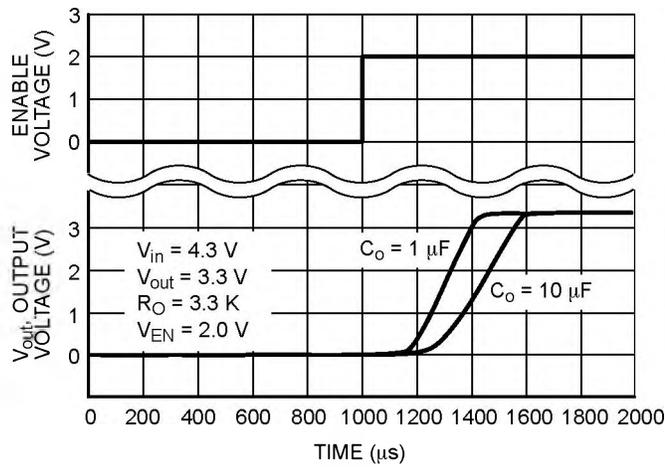


Figure 16. Turn-On Response

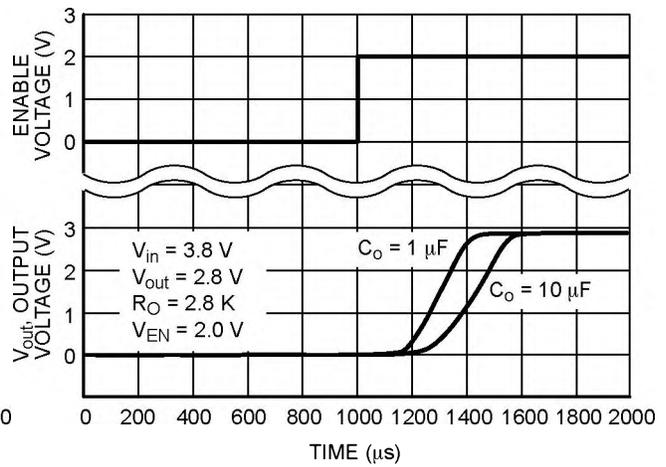


Figure 17. Turn-On Response

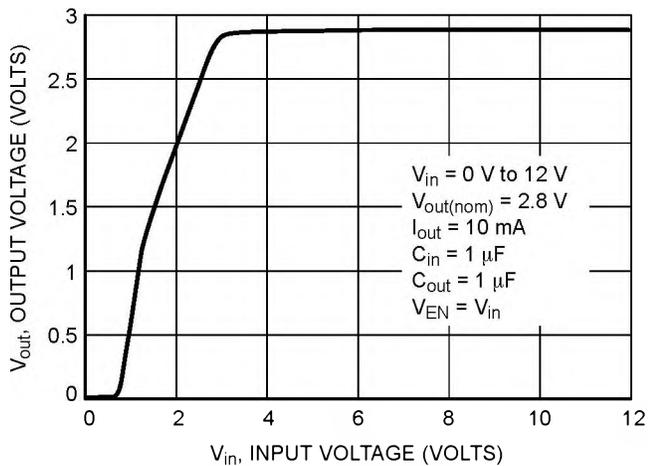


Figure 18. Output Voltage versus Input Voltage

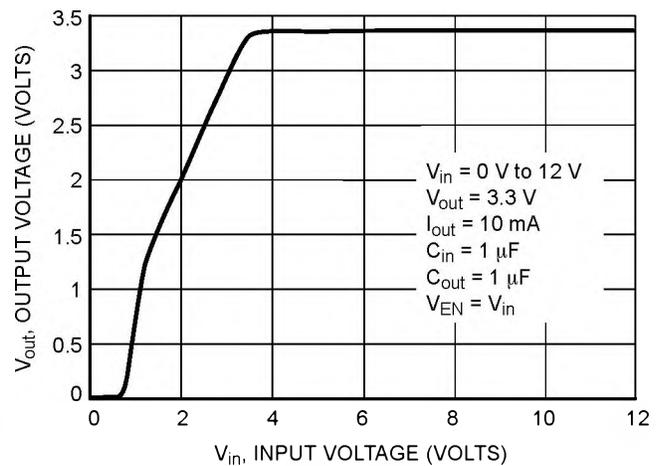


Figure 19. Output Voltage versus Input Voltage

## APPLICATIONS INFORMATION

A typical application circuit for the NCP551 series is shown in Figure 20.

### Input Decoupling (C1)

A 0.1  $\mu\text{F}$  capacitor either ceramic or tantalum is recommended and should be connected close to the NCP551 package. Higher values and lower ESR will improve the overall line transient response.

### Output Decoupling (C2)

The NCP551 is a stable Regulator and does not require any specific Equivalent Series Resistance (ESR) or a minimum output current. Capacitors exhibiting ESRs ranging from a few  $\text{m}\Omega$  up to  $3.0 \Omega$  can thus safely be used. The minimum decoupling value is 0.1  $\mu\text{F}$  and can be augmented to fulfill stringent load transient requirements. The regulator accepts ceramic chip capacitors as well as tantalum devices. Larger values improve noise rejection and load regulation transient response.

### Enable Operation

The enable pin will turn on or off the regulator. These limits of threshold are covered in the electrical specification section of this data sheet. If the enable is not used then the pin should be connected to  $V_{\text{in}}$ .

### Hints

Please be sure the  $V_{\text{in}}$  and Gnd lines are sufficiently wide. When the impedance of these lines is high, there is a chance to pick up noise or cause the regulator to malfunction.

Set external components, especially the output capacitor, as close as possible to the circuit, and make leads as short as possible.

### Thermal

As power across the NCP551 increases, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and also the ambient temperature effect the rate of temperature rise for the part. This is stating that when the NCP551 has good thermal conductivity through the PCB, the junction temperature will be relatively low with high power dissipation applications.

The maximum dissipation the package can handle is given by:

$$PD = \frac{T_{J(\text{max})} - T_A}{R_{\theta JA}}$$

If junction temperature is not allowed above the maximum  $125^\circ\text{C}$ , then the NCP551 can dissipate up to 400 mW @  $25^\circ\text{C}$ .

The power dissipated by the NCP551 can be calculated from the following equation:

$$P_{\text{tot}} = [V_{\text{in}} * I_{\text{gnd}}] + [V_{\text{in}} - V_{\text{out}}] * I_{\text{out}}$$

or

$$V_{\text{inMAX}} = \frac{P_{\text{tot}} + V_{\text{out}} * I_{\text{out}}}{I_{\text{gnd}} + I_{\text{out}}}$$

If a 150 mA output current is needed then the ground current from the data sheet is  $4.0 \mu\text{A}$ . For an NCP551SN30T1 (3.0 V), the maximum input voltage will then be 5.6 V.

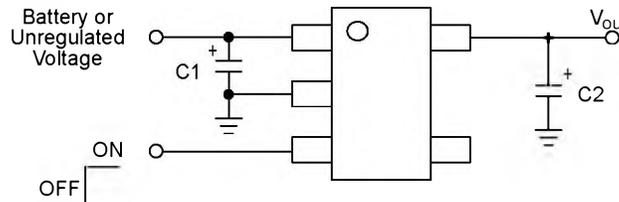
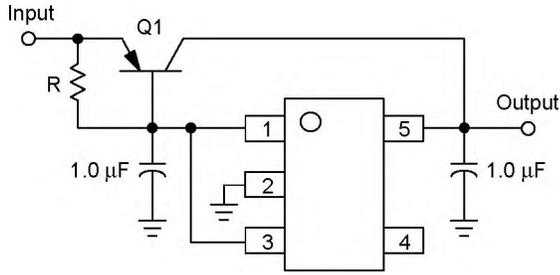
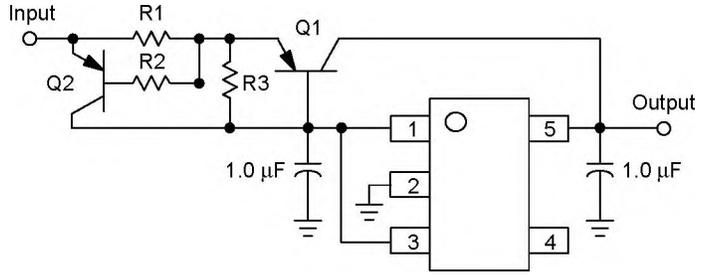


Figure 20. Typical Application Circuit



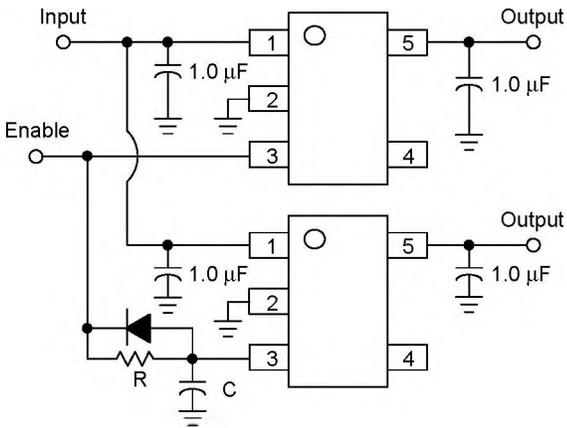
**Figure 21. Current Boost Regulator**

The NCP551 series can be current boosted with a PNP transistor. Resistor R in conjunction with  $V_{BE}$  of the PNP determines when the pass transistor begins conducting; this circuit is not short circuit proof. Input/Output differential voltage minimum is increased by  $V_{BE}$  of the pass resistor.



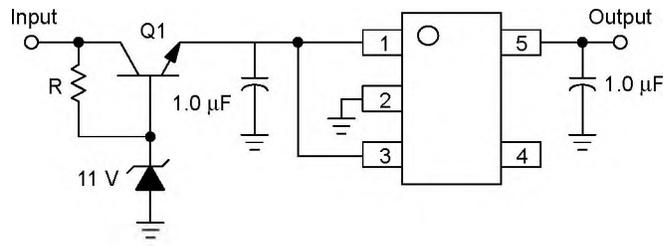
**Figure 22. Current Boost Regulator with Short Circuit Limit**

Short circuit current limit is essentially set by the  $V_{BE}$  of Q2 and R1.  $I_{SC} = ((V_{BEQ2} - i_b \cdot R2) / R1) + I_{O(max)} \text{ Regulator}$



**Figure 23. Delayed Turn-on**

If a delayed turn-on is needed during power up of several voltages then the above schematic can be used. Resistor R, and capacitor C, will delay the turn-on of the bottom regulator.



**Figure 24. Input Voltages Greater than 12 V**

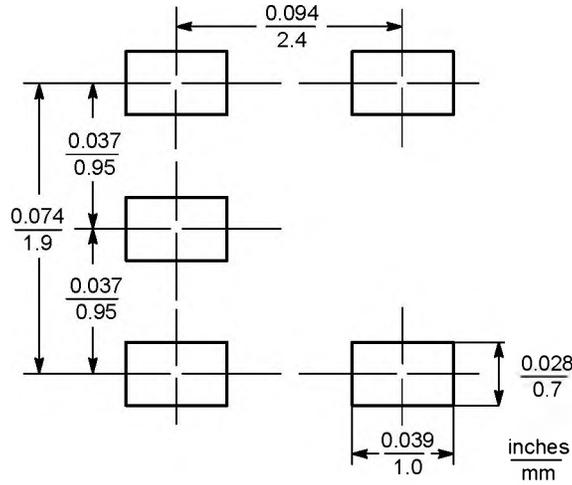
A regulated output can be achieved with input voltages that exceed the 12 V maximum rating of the NCP551 series with the addition of a simple pre-regulator circuit. Care must be taken to prevent Q1 from overheating when the regulated output ( $V_{out}$ ) is shorted to  $G_{nd}$ .

# NCP551

## MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection

interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



### TSOP-5

(Footprint Compatible with SOT23-5)

## ORDERING INFORMATION

Device	Nominal Output Voltage	Marking	Package	Shipping
NCP551SN15T1	1.5	LAO	TSOP-5	3000 Units/7" Tape & Reel
NCP551SN18T1	1.8	LAP		
NCP551SN25T1	2.5	LAQ		
NCP551SN27T1	2.7	LAR		
NCP551SN28T1	2.8	LAS		
NCP551SN30T1	3.0	LAT		
NCP551SN33T1	3.3	LAU		
NCP551SN50T1	5.0	LAV		

Additional voltages in 100 mV steps are available upon request by contacting your ON Semiconductor representative.